**IEET U.S.** Department of Commerce **FORM PTO-1595** 06-04-2002 **Patent and Trademark Office** 1-31-92 Attorney Docket No. 01261.0007 Attorney Customer Number: 22,852 To the Honorable Commissione ATTN. BOX ASSIGNMENTS 102110424 Please record the attached orig. 2. Name and address of receiving party(ies) Name of conveying party(ies): Nam Sik KIM Name: HYNIX SEMICONDUCTOR INC. Additional name(s) of conveying party(ies) attached? Internal Address: Street Address: San 136-1, Ami-ri, Bubal-eu 3. Nature of conveyance: Ichon-shi, Kyoungki-do, 467  $\boxtimes$ City: Assignment Merger Change of Name State: Zip Code: Security Agreement Other: Additional name(s) & Address(es) attached? **Execution Date:** March 18, 2002 ☐ Yes ☑ No 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application: March 18, 2002 A. Patent Application Number(s): B. Patent Number(s): Additional numbers attached? ☐ Yes ☑ No 6. Total number of applications and registrations 5. Name and address of party to whom correspondence concerning document should be mailed: involved: 1 Total fee (37 CFR 3.41): \$40 7. Mr. Ernest F. Chapman Name:  $\boxtimes$ Enclosed (Please charge deficiency to deposit account) Authorized to be charged to deposit account FINNEGAN, HENDERSON, FARABOW, GARRETT Internal Address: & DUNNER, L.L.P. 1300 I Street, N.W. Street Address: Washington, D.C. City: 20005-3315 8. Deposit Account No.: 06-0916 Zip: State: 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. May 28, 2002 Ernest F. Chapman, Reg. No. 25,961 Date

Total number of pages including cover sheet, attachments and documents: 3

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PATENT REEL: 012940 FRAME: 0224

SOLE/JOINT INVENTION (Worldwide Rights) Attorney Docket No.

## **ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled: **SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME** 

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on , 20 (Serial No. ); and

WHEREAS, **Hynix Semiconductor Inc.**, a corporation of Republic of Korea whose post office address is San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Korea (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional application Serial No. , filed (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Page 1 of 2

PATENT REEL: 012940 FRAME: 0225

SOLE/JOINT INVENTION (Worldwide Rights) Attorney Docket No.

County of	Republic of Korea	)	Name:	Nam Sik KIM
-		) ss.	Address:	86-23 Sanbon-1-dong, Gunpo-shi
State of	Kyoungki-do 435-838	)		
State of	Nyoungki-do 455-656	,	By:	Konsansik
			Date:	March 18,2002
Subscribed and sworn to before me this 8th day of March, 20 02				
	, No	tary Public		
So	Young KIM			

Page 2 of 2

PATENT REEL: 012940 FRAME: 0226